

CBR08C299B1GAC

General Information

CBR-SMD RF COG, Ceramic, 2.9 pF, +/-0.1 pF, 100 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0805



CBR-SMD RF COG Series Style SMD Chip Description SMD, Fixed, RF, Ultra High Q, Low ESR, Class I Features Ultra High Q, Low ESR, Class I RoHS Yes Termination Tin Marking No AEC-Q200 No Typical Component Weight 12.03 mg Notes Solder Wave or Solder Reflow. Shelf Life 78 Weeks MSL 1

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	0.85mm +/-0.1mm
В	0.5mm +/-0.2mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape

4000

Specifications	
specifications	
Capacitance	2.9 pF
Tolerance	+/-0.1 pF
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.218%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	458

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

Packaging Quantity